

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application:	:	Group Art Unit: 2811
V. Markovich et al	:	Examiner:
Serial No.: 10/661,616	:	Endicott Interconnect Technologies
Filed: 9/15/03	:	1701 North Street
Title: Stacked Chip Electronic Package Having	:	Endicott, NY 13760
Laminate Carrier and Method of Making Same	:	

Commissioner For Patents
P.O. Box 1450
Arlington, VA 223130-1450

Sir:

STATUS INQUIRY


Applicants request the status of the above application. The application was filed on 09/15/03. A copy of the return postcard is attached for the Examiner's convenience. A Filing Receipt was received 12/12/03. A copy is also attached for the Examiner's convenience.

Because Applicants have heard nothing further as of this date, a status is requested. Please advise when we may expect a communication with respect to the above-referenced application. A stamped, self-addressed envelope is enclosed herewith for your use in responding to this request.

An e-mail response to the undersigned at the email address below or a phone response is encouraged to expedite a response to this inquiry.

Respectfully submitted,

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Certificate of Mailing under 37 CFR 1.8

I hereby certify that this correspondence is being deposited with United States Postal Service in an envelope addressed to:

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On 7/15/04.

Christine Lang
Signature

Christine Lang
Typed or printed name of person of signing Certificate

EI-2-03-001-CIP3 – Status Inquiry, copy of return postcard, stamped, self-addressed envelope, post card

Note: Each paper must have its own certificate of mailing, or this certificate must identify each submitted paper.